

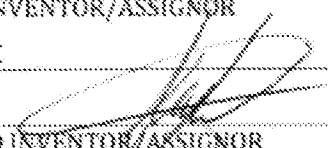
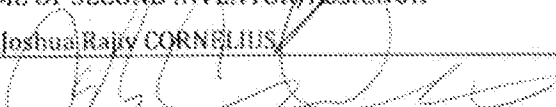
PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT5022028

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MARC EPITAUX	03/09/2016
JOSHUA R. CORNELIUS	03/09/2016
JOHN L. NIGHTINGALE	03/11/2016
RECEIVING PARTY DATA	
Name:	Samtec, Inc.
Street Address:	520 Park East Boulevard
City:	New Albany
State/Country:	INDIANA
Postal Code:	47151-1147
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16016979
CORRESPONDENCE DATA	
Fax Number:	(571)313-7421
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	571-313-7440
Email:	mrhodes@kbiplaw.com
Correspondent Name:	KEATING & BENNETT LLP
Address Line 1:	1800 ALEXANDER BELL DR.
Address Line 2:	SUITE 200
Address Line 4:	RESTON, VIRGINIA 20191
ATTORNEY DOCKET NUMBER:	80505.245.US.CON1
NAME OF SUBMITTER:	MICHELLE RHODES
SIGNATURE:	/PMM/mr/
DATE SIGNED:	06/25/2018
This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 3	
source=80505-245-US-CON1-PTO-20180625-Signed-Declaration-Assignment#page1.tif	
source=80505-245-US-CON1-PTO-20180625-Signed-Declaration-Assignment#page2.tif	

COMBINED DECLARATION/ASSIGNMENT FOR UTILITY OR DESIGN APPLICATION

Title	OPTICAL MODULE INCLUDING SILICON PHOTONICS CHIP AND COUPLER CHIP		
As a below named INVENTOR/ASSIGNOR, I hereby declare that:			
This declaration <input checked="" type="checkbox"/> The attached application, or			
is directed to: <input type="checkbox"/> United States application or PCT international application number _____			
filed on _____			
The above-identified application was made or authorized to be made by me.			
I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.			
I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims.			
I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR § 1.56.			
WHEREAS, <u>SAMTEC, Inc.</u>			
(hereinafter referred to as "ASSIGNEE") having places of business at: <u>520 Park East Boulevard, New Albany, IN 47151-1147</u> , is desirous of acquiring the entire right, title, and interest in, to, and under said invention and any Letters Patent that may be granted therefore in the United States and in any and all foreign countries:			
NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that in consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration, ASSIGNOR hereby sells, assigns, and transfers to ASSIGNEE the full and exclusive right, title, and interest to the said invention and all Letters Patent of the United States to be obtained therefore on said application or any continuation, division, renewal, substitute, or reissue thereof for the full term or terms for which the same may be granted; and all Letters Patent and applications therefore through the world, including all the rights accruing by virtue of the International Convention for the Protection of Industrial Property or other relevant International Treaties and Arrangements.			
ASSIGNOR hereby covenants that no assignment, sale, agreement, or encumbrance has been or will be made or entered into which would conflict with this assignment and sale:			
ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention, and said Letters Patent as may be known and accessible to ASSIGNOR and will testify as to the same in any interference or litigation related thereto and will promptly execute and deliver to ASSIGNEE or its legal representative any and all papers, instruments, or affidavits required to apply for, obtain, maintain, and enforce said application, said invention, and said Letters Patent which may be necessary or desirable to carry out the purposes hereof.			
I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.			
LEGAL NAME OF FIRST INVENTOR/ASSIGNOR			
Inventor:	Marc EPITAUX	Date:	March 9 th 2016
Signature: 			
LEGAL NAME OF SECOND INVENTOR/ASSIGNOR			
Inventor:	Joshua Rajiv CORNELIUS	Date:	3/9/2016
Signature: 			

COMBINED DECLARATION/ASSIGNMENT FOR UTILITY OR DESIGN APPLICATION

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is directed to: <input type="checkbox"/> United States application or PCT international application number _____			
filed on _____			
The above-identified application was made or authorized to be made by me.			
I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.			
I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims.			
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ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention, and said Letters Patent as may be known and accessible to ASSIGNOR and will testify as to the same in any interference or litigation related thereto and will promptly execute and deliver to ASSIGNEE or its legal representative any and all papers, instruments, or affidavits required to apply for, obtain, maintain, and enforce said application, said invention, and said Letters Patent which may be necessary or desirable to carry out the purposes hereof.			
I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.			
LEGAL NAME OF FIRST INVENTOR/ASSIGNOR			
Inventor: <u>Marc EPITAUX</u>		Date: _____	
Signature: _____			
LEGAL NAME OF SECOND INVENTOR/ASSIGNOR			
Inventor: <u>Joshua Rajiv CORNELIUS</u>		Date: _____	
Signature: _____			

LEGAL NAME OF THIRD INVENTOR/ASSIGNOR

Inventor: John L. NIGHTINGALE

Date: March 11, 2016

Signature: *John L. Nightingale*